a sealing member provided between said first substrate and said second substrate for sealing said liquid crystal therebetween, said sealing member enclosing said active matrix circuit and said driver circuit;

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing member and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate.

26. (Amended) The device of claim 25 wherein the thin film transistors of each of said active matrix circuit and said driver circuit are formed [on] over said first substrate through a common process.

28. (Amended) The device of claim 25 wherein [the] a same material as said sealing member is provided [on] over at least said driver circuit.

30. (Amended) An [electro-optical] active matrix type display device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form [on] over said first substrate;

at least one driver circuit for driving said active matrix circuit [on] over said first substrate, each of said active matrix circuit and said driver circuit comprising thin film transistors provided [on] over said first substrate;

a second substrate opposed to said first substrate wherein an electrical element is provided [on] over the second substrate at least at a region opposed to the driver circuit;

a liquid crystal provided between said first substrate and said second substrate;

a sealing member provided between said first substrate and said second substrate for sealing said liquid crystal therebetween, said sealing member enclosing said active matrix circuit and said driver circuit;

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing member and on a side of said first substrate and said second substrate,

wherein an outer edge of said sealing member is located inside side edges of said first and second substrates, and

wherein an electrical connection is established between said driver circuit and said electrical element by at least one silver paste or at least one electrically conductive spacer.

31. (Amended) The device of claim 30 wherein the thin film transistors of each of said active matrix circuit and said driver circuit are formed [on] over said [second] first substrate through a common process.

33. (Amended) The device of claim 30 wherein [the] a same material as said sealing member is provided [on] over at least said driver circuit.

35. (Amended) An [electro-optical] active matrix type display device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form [on] over said first substrate;

at least one driver circuit for driving said active matrix circuit [on] over said first substrate, there being at least one side of said first substrate at which no driver circuit is disposed, and each of said active matrix circuit and said driver circuit comprising thin film transistors provided [on] over said first substrate;

a second substrate opposed to said first substrate wherein an electrical element is provided [on] over the second substrate at least at a region opposed to the driver circuit;

a liquid crystal provided between said first substrate and said second substrate;

a sealing member provided between said first substrate and said second substrate for sealing said liquid crystal therebetween, said sealing member enclosing said active matrix circuit and said driver circuit; and

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing member and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate,

wherein said second substrate has at least one side edge which is substantially aligned with a side edge of said first substrate and an outer edge of said sealing member, and

wherein an electrical connection is established between said driver circuit and said electrical element by at least one silver paste or at least one electrically conductive spacer.

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38. (Amended) The device of claim 35 wherein [the] a same material as said sealing member is provided [on] over at least said driver circuit.

40. (Amended) An [electro-optical] active matrix type display device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form [on] over said first substrate;

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at least one driver circuit for driving said active matrix circuit [on] over said first substrate, there being at least one side of said first substrate at which no driver circuit is disposed, and each of said active matrix circuit and said driver circuit comprising thin film transistors provided [on] over said first substrate;

a second substrate opposed to said first substrate;

a liquid crystal provided between said first substrate and said second substrate;

a resin material provided between said first and second substrates, said resin material [contacting with said second substrate and] covering said driver circuit;

a sealing member provided between said first substrate and said second substrate and enclosing said active matrix circuit and said driver circuit; and

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing member and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate.

41. (Amended) An [electro-optical] active matrix type display device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form [on] over said first substrate;

at least one driver circuit for driving said active matrix circuit [on] over said first substrate, each of said active matrix circuit and said driver circuit comprising thin film transistors provided [on] over said first substrate;

a second substrate opposed to said first substrate wherein an electrical element is provided [on] over the second substrate at least at a region opposed to the driver circuit;

a liquid crystal provided between said first substrate and said second substrate;

a resin material provided between said first and second substrates, said resin material [contacting with said second substrate and] covering said driver circuit;

a sealing member provided between said first substrate and said second substrate and enclosing said driver circuit; and

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing member and on a side edge of said first substrate and said second substrate, and

wherein an electrical connection is established between said driver circuit and said electrical element by at least one silver paste or at least one electrically conductive spacer.

42. (Amended) An [electro-optical] <u>active matrix type display</u> device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form [on] <u>over</u> said first substrate;

at least one driver circuit for driving said active matrix circuit [on] <u>over</u> said first substrate, there being at least one side of said first substrate at which no driver circuit is disposed, and each of said active matrix circuit and said driver circuit comprising thin film transistors provided [on] <u>over</u> said first substrate;

a second substrate opposed to said first substrate wherein an electrical element is provided [on] <u>over</u> the second substrate at least at a region opposed to the driver circuit;

a liquid crystal provided between said first substrate and said second substrate;

a resin material provided between said first and second substrates, said resin material [contacting with said second substrate and] covering said driver circuit;

a sealing member provided between said first substrate and said second substrate and enclosing said active matrix circuit and said driver circuit;

a first inlet provided for introducing said liquid crystal between said first substrate and said second substrate; and

a second inlet provided for introducing said resin material between said first substrate and said second substrate,

wherein said first inlet is provided to said sealing member and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate, and

wherein an electrical connection is established between said driver circuit and said electrical element by at least one silver paste or at least one electrically conductive spacer.

43. (Amended) An [electro-optical] active matrix type display device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form [on] over said first substrate;

at least one first driver circuit for driving said active matrix circuit [on] over said first substrate, each of said active matrix circuit and said first driver circuit comprising thin film transistors provided [on] over said first substrate;

a second substrate opposed to said first substrate wherein a [drive] second driver circuit is provided [on] over the second substrate at a region opposed to the first driver circuit;

a liquid crystal provided between said first substrate and said second substrate;

a resin material provided between said first and second substrates, said resin material [contacting with said second substrate and] covering said first driver circuit; and

a sealing member provided between said first substrate and said second substrate and enclosing said active matrix circuit and said first driver [circuits] circuit.

44. (Amended) An [electro-optical] active matrix type display device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form [on] over said first substrate;

at least one first driver circuit for driving said active matrix circuit [on] over said first substrate, each of said active matrix circuit and said first driver circuit comprising thin film transistors provided [on] over said first substrate;

a second substrate opposed to said first substrate wherein a [drive] second circuit is provided [on] over the second substrate at a region opposed to the first driver circuit;

a resin material provided between said first and second substrates, said resin material [contacting with said second substrate and] covering said first driver circuit; and

a sealing member provided between said first substrate and said second substrate and enclosing said first driver circuit;

a liquid crystal provided between said first substrate and said second substrate.

56. (Amended) An [electro-optical] active matrix type display device comprising

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form [on] over said first substrate, there being at least one side of said first substrate at which no first driver circuit is disposed, and each of said active matrix circuit and said first driver circuit comprising thin film transistors provided [on] over said first substrate;

a second substrate opposed to said first substrate wherein a second driver circuit is provided [on] over the second substrate at a region opposed to the first driver circuit;

a liquid crystal provided between said first substrate and said second substrate;

a sealing member provided between said first substrate and said second substrate for sealing said liquid crystal therebetween, said sealing member enclosing said active matrix circuit and said first driver circuit;

an inlet for injecting said liquid crystal between said first substrate and said second substrate,

wherein said inlet is provided to said sealing member and on a side edge of said first substrate and said second substrate corresponding to said one side of said first substrate.

57. (Amended) The device of claim 56 wherein the thin film transistors of each of said active matrix circuit and said first driver circuit are formed [on] over said first substrate through a common process.

59. (Amended) The device of claim 56 wherein [the] a same material as said sealing member is provided [on] over at least said first driver circuit.

REMARKS

Claims 13-15 and 18-60 are pending in this application. By this Amendment, claims 25, 26, 28, 30, 31, 33, 35, 38, 40-44, 56, 57 and 59 are amended. Reconsideration in view of the above amendments and following remarks is respectfully solicited.

Applicants gratefully acknowledge the Office Action's indication of allowable subject matter in claims 56-60.